PMR210, Metallized Impregnated Paper, Class X1, 250 VAC



Overview

Multilayer metallized paper encapsulated and impregnated in self-extinguishing material that meets the requirements of UL 94 V-0.

Applications

For worldwide use in contact protection, contact interference suppression, and transient suppression.

Benefits

· Approvals: ENEC, UL, cUL

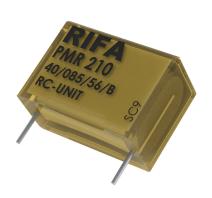
· Rated voltage: 250 VAC 50/60 Hz Capacitance range: 0.022 – 0.1 μF • Capacitance tolerance: ±20% • Resistance range: 100 Ω Resistance tolerance: ±30%

• Lead Spacing: 15.2 - 25.4 mm Climatic category: 40/085/56/B, IEC 60068-1

• Tape and reel packaging in accordance with IEC 60286-2

· RoHS compliance and lead-free terminations

• Operating temperature range of -40°C to +85°C



Legacy Part Number System

PMR210	M	В	5220	M	100	R30
Series	Rated Voltage (VAC)	Lead Spacing (mm)	Capacitance Code (pF)	Capacitance Tolerance	Resistance (Ω)	Packaging
RC Snubber, Metallized Paper	M = 250	B = 15.2 C = 20.3 E = 25.4	The last three digits represent significant figures. The first digit specifies the total number of digits.	M = ±20%	Resistance value in Ω	See Ordering Options Table

New KEMET Part Number System

P	410	Q	M	223	M	250	A	H101
Capacitor Class	Series	Lead Spacing (mm)	Size Code	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VAC)	Lead and Packaging Code	Resistance (Ω)
P = Metallized Paper	RC Snubber	Q = 15.2 C = 20.3 E = 25.4	See Dimension Table	First two digits represent significant figures. Third digit specifies number of zeros.	M = ±20%	250 = 250	See Ordering Options Table	H plus first two digits represent significant figures. Third digit specifies number of zeros.



Benefits cont'd

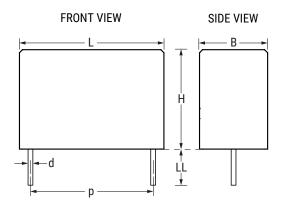
- Excellent self-healing properties that ensure long life, even High dv/dt capability when subjected to frequent over-voltages
- Good resistance to ionization due to impregnated paper dielectric
- Impregnated paper that ensures excellent stability and reliability properties, particularly in applications with continuous operation

Ordering Options Table

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	KEMET Lead and Packaging Code	Legacy Lead and Packaging Code
	Standard Lead and Packaging Options			
15.2	Bulk (Bag) – Short Leads	6 +0/-1	С	R06
13.2	Bulk (Bag) – Maximum Length Leads	30 +5/-0	Α	R30
	Tape & Reel (Standard Reel Φ = 360 mm)	H ₀ = 18.5 ±0.5	L	R19T0
			T .	
	Standard Lead and Packaging Options			
20.3	Bulk (Tray) – Short Leads	6 +0/-1	С	R06
20.0	Bulk (Bag) – Maximum Length Leads	30 +5/-0	Α	R30
	Tape & Reel (Standard Reel Φ = 360 mm)	H ₀ = 18.5 ±0.5	L	R19T0
	Standard Lead and Packaging Options			
25.4	Bulk (Bag) – Short Leads	6 +0/-1	С	R06
	Bulk (Tray) – Maximumn Length Leads	30 +5/-0	Α	R30



Dimensions - Millimeters



Size Code	р		В		Н		L		d	
	Nominal	Tolerance								
QM	15.2	±0.4	7.3	Maximum	13.0	Maximum	18.5	Maximum	0.8	±0.05
QS	15.2	±0.4	8.5	Maximum	14.3	Maximum	18.5	Maximum	0.8	±0.05
CJ	20.3	±0.4	9.0	Maximum	15.0	Maximum	24.0	Maximum	0.8	±0.05
CP	20.3	±0.4	11.3	Maximum	16.5	Maximum	24.0	Maximum	0.8	±0.05
EE	25.4	±0.4	10.6	Maximum	16.1	Maximum	30.5	Maximum	1.0	±0.05

Note: See the Ordering Options Table for lead length (LL) options.



Performance Characteristics

Rated Voltage	250 VAC 50/60 Hz					
Capacitance Range	0.022 - 0.1 μF					
Capacitance Tolerance	±20%					
Resistance Range	100 Ω					
Resistance Tolerance	±30%					
Temperature Range	-40°C to +85°C					
Climatic Category	40/085/56/B					
Approvals	ENEC, UL, cUL					
Peak Pulse Voltage	1,000 V					
Series Resistance	The series resistance is defined 100 kHz for RC < 50 µs	at 1 kHz for RC ≥ 50 µs and at				
Insulation Resistance	Minimum Value Between Terminals					
modution resistance	·	00 ΜΩ				
Pulse Current	Maximum 12 A repetitive. Maxim transients.	num 20 A peak for occasional				
Test Voltage Between Terminals	The 100% screening factory test is carried out at 3,000 VDC. The voltage level is selected to meet the requirements in applicaple equipment standards. All electrical characteristics are checked after the test.					
In DC Applications	Recommended voltage ≤ 1,000 V	/DC				
Power Ratings	Average losses may reach 0.5 W temperature does not exceed +8 power dissipation versus temper	35°C. For maximum permitted				
Derating Curves	Maximum Allowable Power Diss Temperature and Case Sizes. Pmax W 1 2 3 0.5 Curve 1 1 2 3	Dimension B (mm) 7.3 8.5 9.0 11.3				
	1 8.5 2 9.0					



Environmental Test Data

Test	IEC Publication	Procedure				
Endurance	IEC 60384-14	$1.25 \times V_R$ VAC 50 Hz, once every hour increased to 1,000 VAC for 0.1 second, 1,000 hours at upper rated temperature.				
Vibration	IEC 60068-2-6 Test Fc	3 directions at 2 hours each, 10 – 500 Hz at 0.75 mm or 98 m/s²				
Bump	IEC 60068-2-29 Test Eb	4,000 bumps at 390 m/s ²				
Change of Temperature	IEC 60068-2-14 Test Na	Upper and lower rated temperature, 5 cycles				
Active Flammability	IEC 60384-14	V _R +20 surge pulses at 4.0 kV (pulse every 5 seconds)				
Passive Flammability	IEC 60384-14	IEC 60384-1, IEC 60695-11-5 Needle-flame test				
Damp Heat Steady State	IEC 60068-2-78 Test Cab	+40°C and 93% RH, 56 days				

Approvals

Certification Body	Mark	Specification	File Number	
Intertek Semko AB		EN/IEC 60384-14	SE/0140-21D	
UL	c Al us	UL 60384-14 CAN/CSA-E60384-14-09	E73869	

Environmental Compliance

All KEMET EMI capacitors are RoHS Compliant.



Table 1 - Ratings & Part Number Reference

Lead	Capacitance	Resistance	Maximun	n Dimensio	ns in mm	New KEMET	Logov Port Number
Spacing (p)	Value (µF)	(Ω)	В	Н	L	Part Number	Legacy Part Number
15.2	0.022	100	7.3	13.0	18.5	P410QM223M250(1)H101	PMR210MB5220M100(1)
15.2	0.033	100	8.5	14.3	18.5	P410QS333M250(1)H101	PMR210MB5330M100(1)
20.3	0.047	100	9.0	15.0	24.0	P410CJ473M250(1)H101	PMR210MC5470M100(1)
20.3	0.068	100	11.3	16.5	24.0	P410CP683M250(1)H101	PMR210MC5680M100(1)
25.4	0.1	100	10.6	16.1	30.5	P410EE104M250(1)H101	PMR210ME6100M100(1)

(1) Insert lead and packaging code. See Ordering Options Table for available options.



Soldering Process

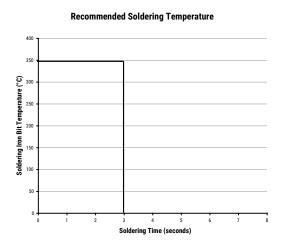
The implementation of the RoHS directive has resulted in the selection of SnAuCu (SAC) alloys or SnCu alloys as primary solder. This has increased the liquidus temperature from that of 183°C for SnPb eutectic alloy to 217 – 221°C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher pre-heat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is 160 – 170°C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 – 15 mm), and great care must be taken during soldering. The recommended solder profiles from KEMET should be used. Consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760-1 Edition 2 serves as a solid guideline for successful soldering. See Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the recommended limits may result in degradation of or permanent damage to the capacitors.

Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface-mount components. Insert through-hole parts after curing the surface-mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum of two soldering cycles is recommended. Allow time for the capacitor surface temperature to return to a normal temperature before the second soldering cycle.

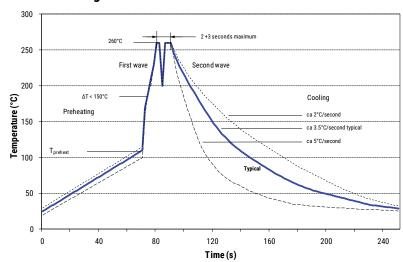
Manual Soldering Recommendations

Following is the recommendation for manual soldering with a soldering iron.



Soldering iron tip temperature should be set at 350°C (+10°C maximum), with the soldering duration not to exceed more than 3 seconds.

Wave Soldering Recommendations





Soldering Process cont'd

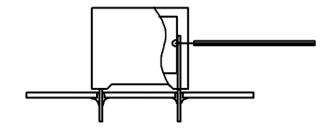
Wave Soldering Recommendations cont'd

1. The table indicates the maximum setup temperature for the soldering process.

Dielectric film	Maximun	n Preheat Tem	Maximum Peak Soldering Temperature			
material	Capacitor Pitch ≤ 10 mm	Capacitor Pitch = 15 mm	Capacitor Pitch > 15 mm	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	
Polyester	130°C	130°C	130°C	270°C	270°C	
Polypropylene	100°C	110°C	130°C	260°C	270°C	
Paper	130°C 130°C 140°C			270°C	270°C	
Polyphenylene Sulphide	150°C	150°C	270°C	270°C		

2. The maximum temperature measured inside the capacitor: set the temperature so that inside the element the maximum temperature is below the limit.

Dielectric Film Material	Maximum Temperature Measured Inside the Element
Polyester	160°C
Polypropylene	110°C
Paper	160°C
Polyphenylene Sulphide	160°C



Temperature monitored inside the capacitor.

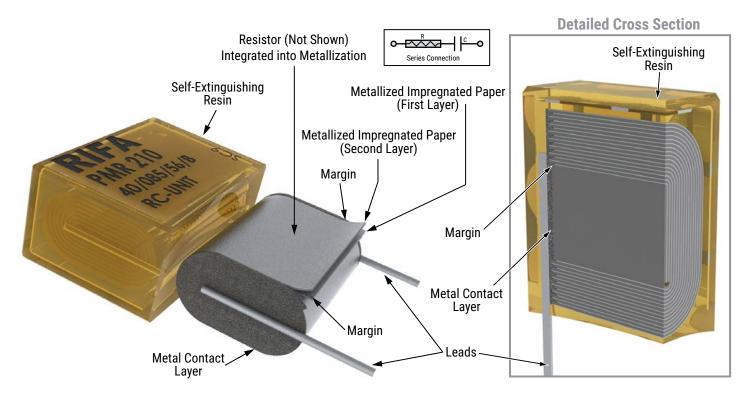
Selective Soldering Recommendations

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath, as in normal flow soldering, without touching the solder. When the board is over the bath, it is stopped. Pre-designed solder pots are lifted from the bath with molten solder, only at the places of the selected components, and pressed against the lower surface of the board to solder the components.

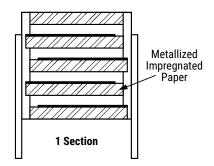
The temperature profile for selective soldering is similar to the double wave flow soldering outlined in this document. **However, instead of two baths, there is only one with a time from 3 to 10 seconds.** In selective soldering, the risk of overheating is greater than in double wave flow soldering. Great care must be taken so that the parts do not overheat.



Construction

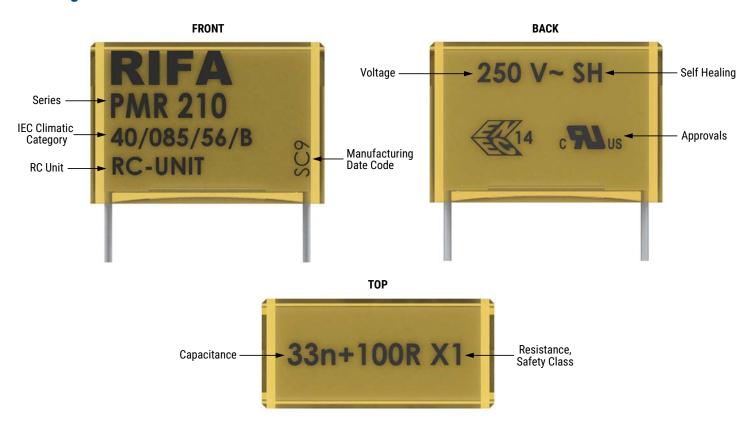


Winding Scheme





Marking



Packaging Quantities

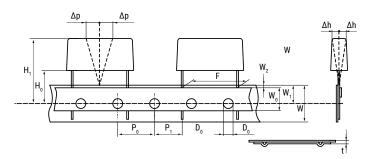
Size Code	Lead Spacing (mm)	Thickness (mm)	Height (mm)	Length (mm)	Bulk Short Leads	Bulk Long Leads	Standard Reel 360 mm
	Lead an	d Packaging Co	de		C/R06	A/R30	L/R19T0
QM	15.2	7.3	13.0	18.5	600	400	400
QS	15.2	8.5	14.3	18.5	500	300	350
CJ	20.3	9.0	15.0	24.0	1,530	200	250
CP	20.3	11.3	16.5	24.0	1,080	150	180
							·
EE	25.4	10.6	16.1	30.5	1,008	150	



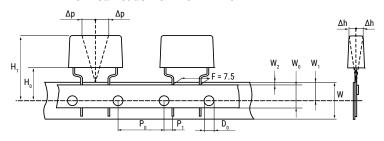
Lead Taping & Packaging (IEC 60286-2)

Lead Spacing 10.2 - 15.2 mm

Lead Spacing 20.3 - 22.5 mm



Formed Leads from 10.2 - 7.5 mm



Taping Specification

	Standard IEC 60286-2							
Lead Spacing	+6/-0.1	F	Formed 7.5	10.2	15.2	20.3	22.5	F
Carrier Tape Width	±0.5	W	18.0	18.0	18.0	18.0	18.0	18 +1/-0.5
Hold-Down Tape Width	Minimum	W _o	5.0	5.0	5.0	5.0	5.0	
Position of Sprocket Hole	±0.5	W ₁	9.0	9.0	9.0	9.0	9.0	9 +0.75/-0.5
Distance Between Tapes	Maximum	W_2	3.0	3.0	3.0	3.0	3.0	3.0
Sprocket Hole Diameter	±0.2	D_{o}	4.0	4.0	4.0	4.0	4.0	4.0
Feed Hole Lead Spacing	±0.3	P ₀ ⁽¹⁾	12.7(4)	12.7	12.7	12.7	12.7	12.7
Distance Lead - Feed Hole	±0.7	P ₁	3.75	7.6	5.1	8.9	5.3	P ¹
Deviation Tape - Plane	Maximum	Δр	1.3	1.3	1.3	1.3	1.3	1.3
Lateral Deviation	Maximum	Δh	2.0	2.0	2.0	2.0	2.0	2.0
Total Thickness	±0.2	t	0.7	0.7	0.7	0.7	0.9 Maximum	0.9 Maximum
Sprocket Hole/Cap Body	Nominal	H ₀ ⁽²⁾	18 +2/-0	18 +2/-0	18 +2/-0	18 +2/-0	18.5 ±0.5	18 +2/-0
Sprocket Hole/Top of Cap Body	Maximum	H ₁ ⁽³⁾	43	43	43	58	58	58 Maximum

⁽¹⁾ Maximum cumulative feed hole error, 1 mm per 20 parts

^{(2) 16.5} mm available on request

⁽³⁾ Depending on case size

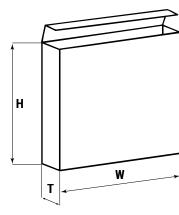
^{(4) 15} mm available on request



Lead Taping & Packaging (IEC 60286-2) cont'd

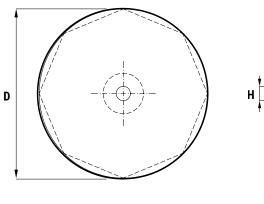
Ammo Specifications

Series	Dimensions (mm)		
Series	Н	W	T
R4x, R4x+R, R7x, RSB			
F5A, F5B, F5D	360	340	59
F6xx, F8xx			
PHExxx, PMExxx, PMRxxx	330	330	50



Reel Specifications

Carias	Dimensions (mm)		
Series	D	Н	W
R4x, R4x+R, R7x, RSB	055		
F5A, F5B, F5D	355 500	30 25	55 (Max)
F6xx, F8xx	300	23	
PHExxx, PMExxx, PMRxxx	360 500	30	46 (Max)



Manufacturing Date Code (IEC-60062)

Y = Year, Z = Month					
Year	Code	Month	Code		
2010	Α	January	1		
2011	В	February	2		
2012	С	March	3		
2013	D	April	4		
2014	E	May	5		
2015	F	June	6		
2016	Н	July	7		
2017	J	August	8		
2018	K	September	9		
2019	L	October	0		
2020	M	November	N		
2021	N	December	D		
2022	Р				
2023	R				
2024	S				
2025	T				
2026	U				
2027	V				
2028	W				
2029	X				
2030	Α				



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